

SEMIPACK® 2

Rectifier Diode Modules

SKKD 212/12

Features*

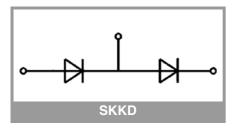
- Heat transfer through aluminum oxide ceramic insulated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E63532

Typical Applications

- Non-controllable rectifiers for AC/AC converters
- Line rectifiers for transistorized AC motor controllers
- Field supply for DC motors

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Recitifier	Diode							
I _{FAV}	sin. 180° T _{j max} = 135 °C	T _c = 85 °C	213	Α				
		T _c = 100 °C	165	Α				
I _{FSM}	10 ms	T _j = 25 °C	6600	Α				
		T _j = 135 °C	5500	А				
i ² t	10 ms	T _j = 25 °C	217800	A ² s				
		T _j = 135 °C	151250	A ² s				
V_{RSM}	T _j = 25 °C		1300					
V_{RRM}	T _j = 25 °C		1200	V				
Tj			-40 135	°C				
Module								
T _{stg}			-40 125	°C				
V _{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V				
	a.c., 50 172, 1.111.5.	1 s	3600	V				

Characte	eristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Diode	•		•			
V_{F}	$T_j = 25 ^{\circ}\text{C}, I_F = 500 \text{A}$				1.40	V
V_{F0}	T _j = 135 °C				0.75	V
r _F	T _j = 135 °C				1.05	mΩ
I _R	$T_j = 135$ °C, $V_{RD} = V_{RRM}$				9	mA
$R_{\text{th(j-c)}}$	cont.	per chip			0.18	K/W
		per module			0.09	K/W
R _{th(j-c)}	sin. 180°	per chip			0.18	K/W
		per module			0.09	K/W
Module	•	•				
$R_{\text{th(c-s)}}$	chip			0.1		K/W
	module			0.05		K/W
Ms	to heatsink M5		4.25		5.75	Nm
Mt	to terminals M6		4.25		5.75	Nm
а					5 * 9.81	m/s²
W				165		g



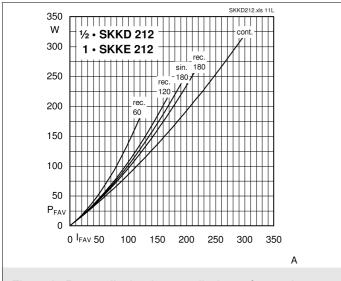


Fig. 11L: Power dissipation per diode vs. forward current

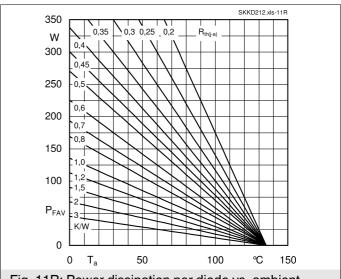


Fig. 11R: Power dissipation per diode vs. ambient temperature

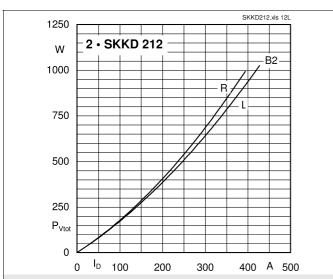


Fig. 12L: Power dissipation of two modules vs. direct current

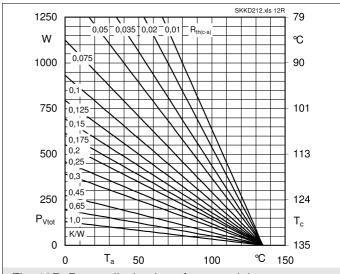


Fig. 12R: Power dissipation of two modules vs. case temperature

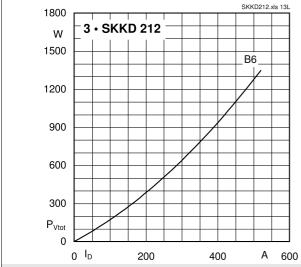


Fig. 13L: Power dissipation of three modules vs. direct current

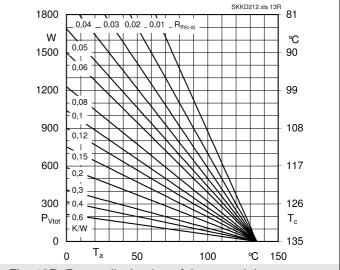


Fig. 13R: Power dissipation of three modules vs. case temperature

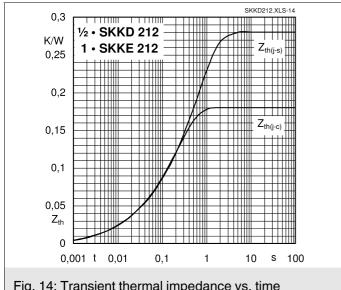


Fig. 14: Transient thermal impedance vs. time

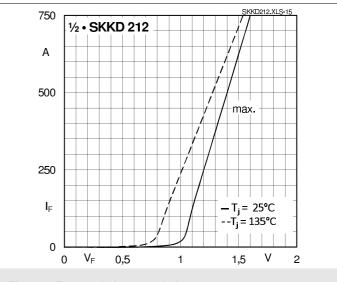
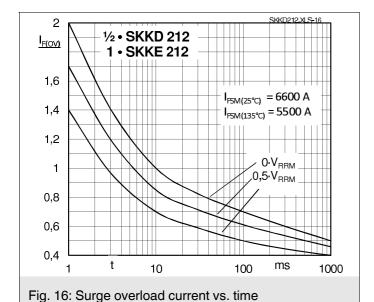
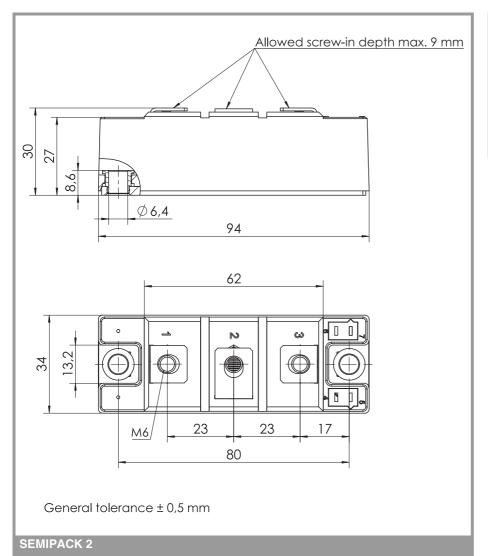
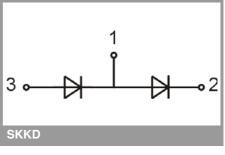


Fig. 15: Forward characteristics



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This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

*IMPORTANT INFORMATION AND WARNINGS

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